



US00D459705S

(12) **United States Design Patent**  
**Yokota et al.**

(10) **Patent No.:** **US D459,705 S**

(45) **Date of Patent:** **\*\* Jul. 2, 2002**

(54) **SEMICONDUCTOR PACKAGE**

(75) **Inventors:** **Yoshio Yokota; Nobuyuki Yokote**, both of Hanno (JP)

(73) **Assignee:** **Shindengen Electric Manufacturing Co., Ltd.**, Tokyo (JP)

(\*\*) **Term:** **14 Years**

(21) **Appl. No.:** **29/142,698**

(22) **Filed:** **Jun. 1, 2001**

(30) **Foreign Application Priority Data**

Mar. 6, 2001 (JP) ..... 2001-005455

(51) **LOC (7) Cl.** ..... **13-03**

(52) **U.S. Cl.** ..... **D13/182**

(58) **Field of Search** ..... D13/182; D14/114; 174/52.1, 52.2, 52.4, 52.5, 16.3; 206/710, 719; 257/254, 659, 697, 730, 738; 324/755, 765; 361/752, 798, 820, 718, 730

(56) **References Cited**

**U.S. PATENT DOCUMENTS**

3,602,846	A	*	8/1971	Hauser	.....	333/140
3,846,734	A	*	11/1974	Pauza et al.	.....	439/70
4,391,408	A	*	7/1983	Hanlon et al.	.....	439/268
4,441,119	A	*	4/1984	Link	.....	257/666
D288,922	S	*	3/1987	Olla	.....	D13/182
4,951,122	A	*	8/1990	Tsubosaki et al.	.....	257/792
4,979,016	A	*	12/1990	Lee	.....	257/668
4,987,474	A	*	1/1991	Yasuhara et al.	.....	257/666
D317,592	S	*	6/1991	Yoshizawa	.....	D13/182
5,337,216	A	*	8/1994	McIver	.....	361/728
5,387,814	A	*	2/1995	Baudouin et al.	.....	257/690
D357,901	S	*	5/1995	Horman	.....	D13/182
5,539,250	A	*	7/1996	Kitano et al.	.....	257/666

5,646,443	A	*	7/1997	Takahashi	.....	257/704
D401,567	S	*	11/1998	Farnworth et al.	.....	D13/182
D401,912	S	*	12/1998	Majumdar et al.	.....	D13/182
5,959,842	A	*	9/1999	Leonard et al.	.....	361/752
6,018,191	A	*	1/2000	Murakami et al.	.....	257/691
6,303,982	B2	*	10/2001	Murakami et al.	.....	257/666

**OTHER PUBLICATIONS**

Japanese Design Application No. 929231, Publication Date: Jul. 6, 1995.

Japanese Design Application No. 982886—Similar 1, Publication Date: Jun. 24, 1997.

Japanese Design Application No. 982886, Publication Date: Jun. 17, 1997.

\* cited by examiner

*Primary Examiner*—Ted Shooman

*Assistant Examiner*—Selina Sikder

(74) *Attorney, Agent, or Firm*—Antonelli, Terry, Stout & Kraus, LLP

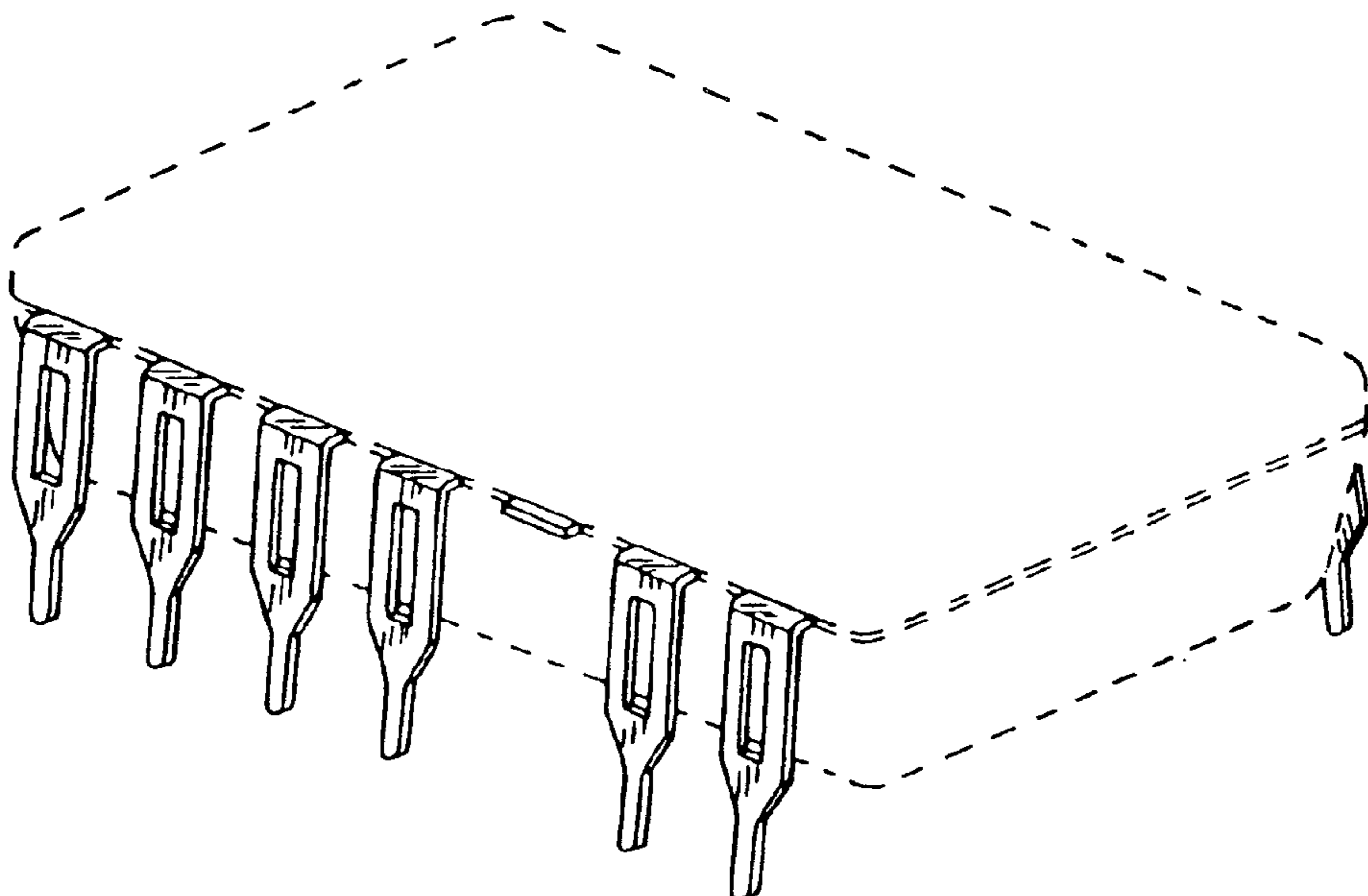
(57) **CLAIM**

The ornamental design for a semiconductor package, as shown and described.

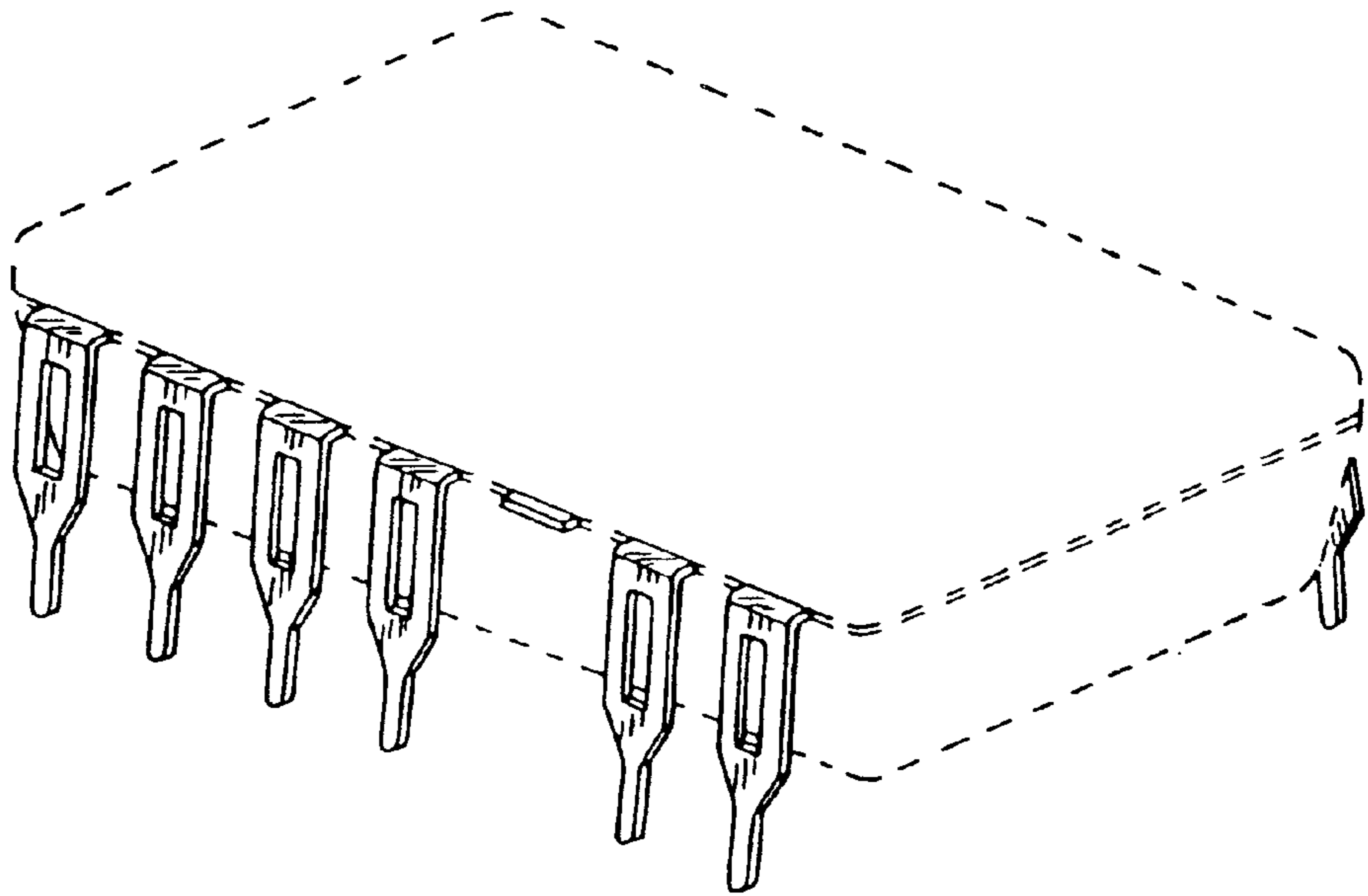
**DESCRIPTION**

FIG. 1 is a front, plan and right side perspective view of a semiconductor package showing our new design; FIG. 2 is a front elevational view thereof; FIG. 3 is a rear elevational view thereof; FIG. 4 is a top plan view thereof; FIG. 5 is a bottom plan view thereof; FIG. 6 is a left side elevational view thereof; and, FIG. 7 is a right side elevational view thereof. The broken lines are shown in the views for illustrative purposes only and form no part of the claimed design.

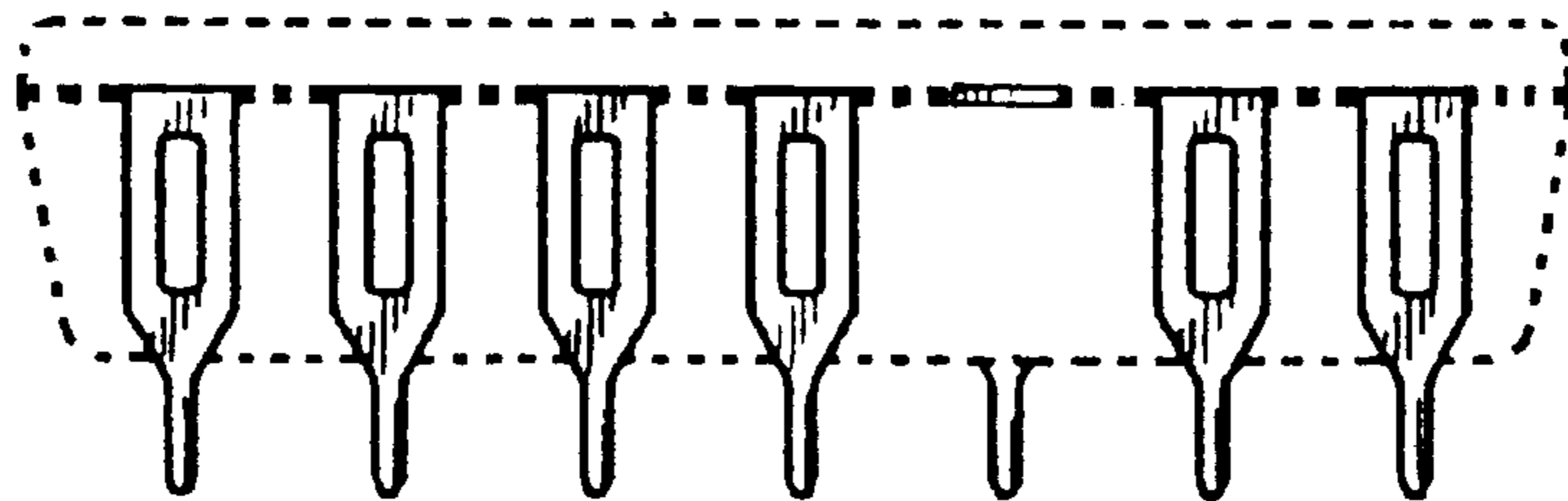
**1 Claim, 2 Drawing Sheets**



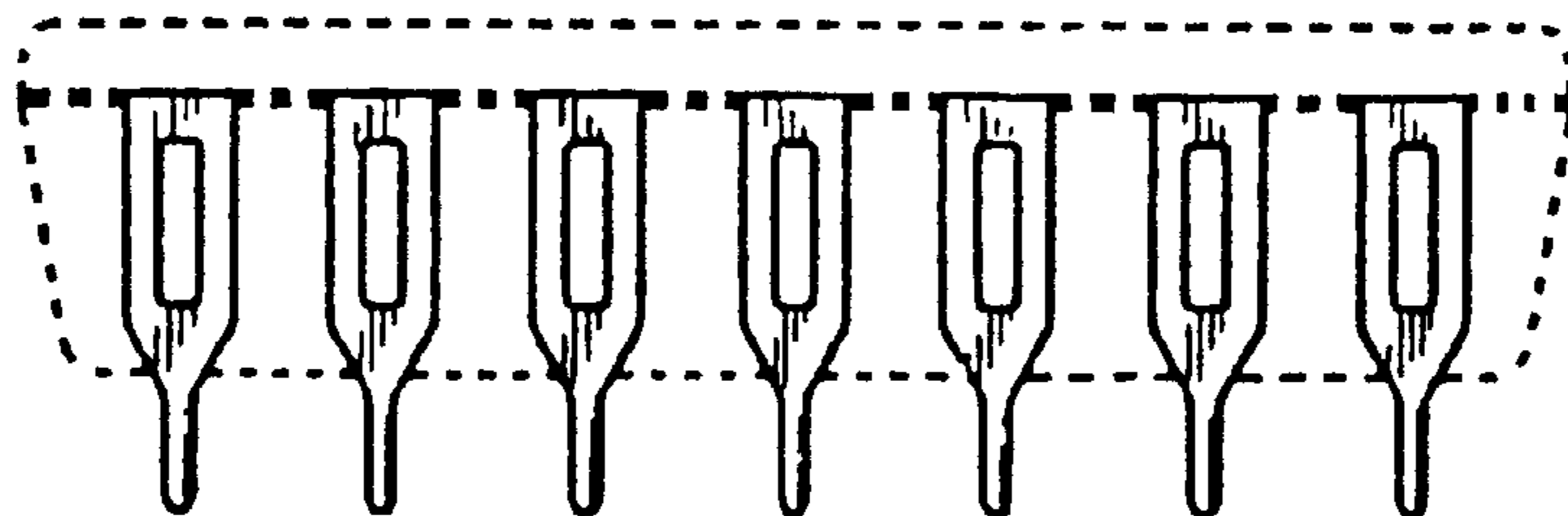
**FIG. 1**



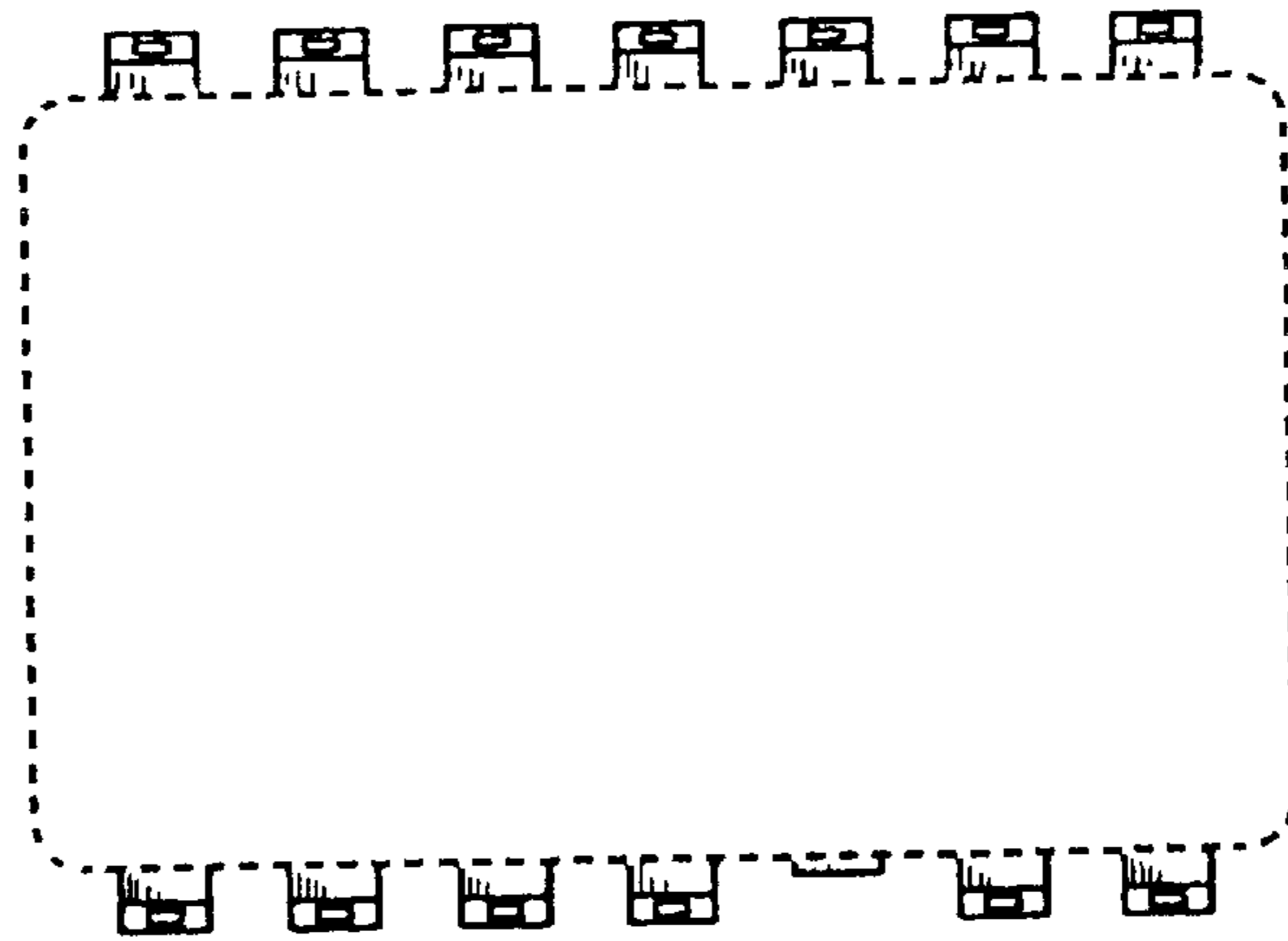
**FIG. 2**



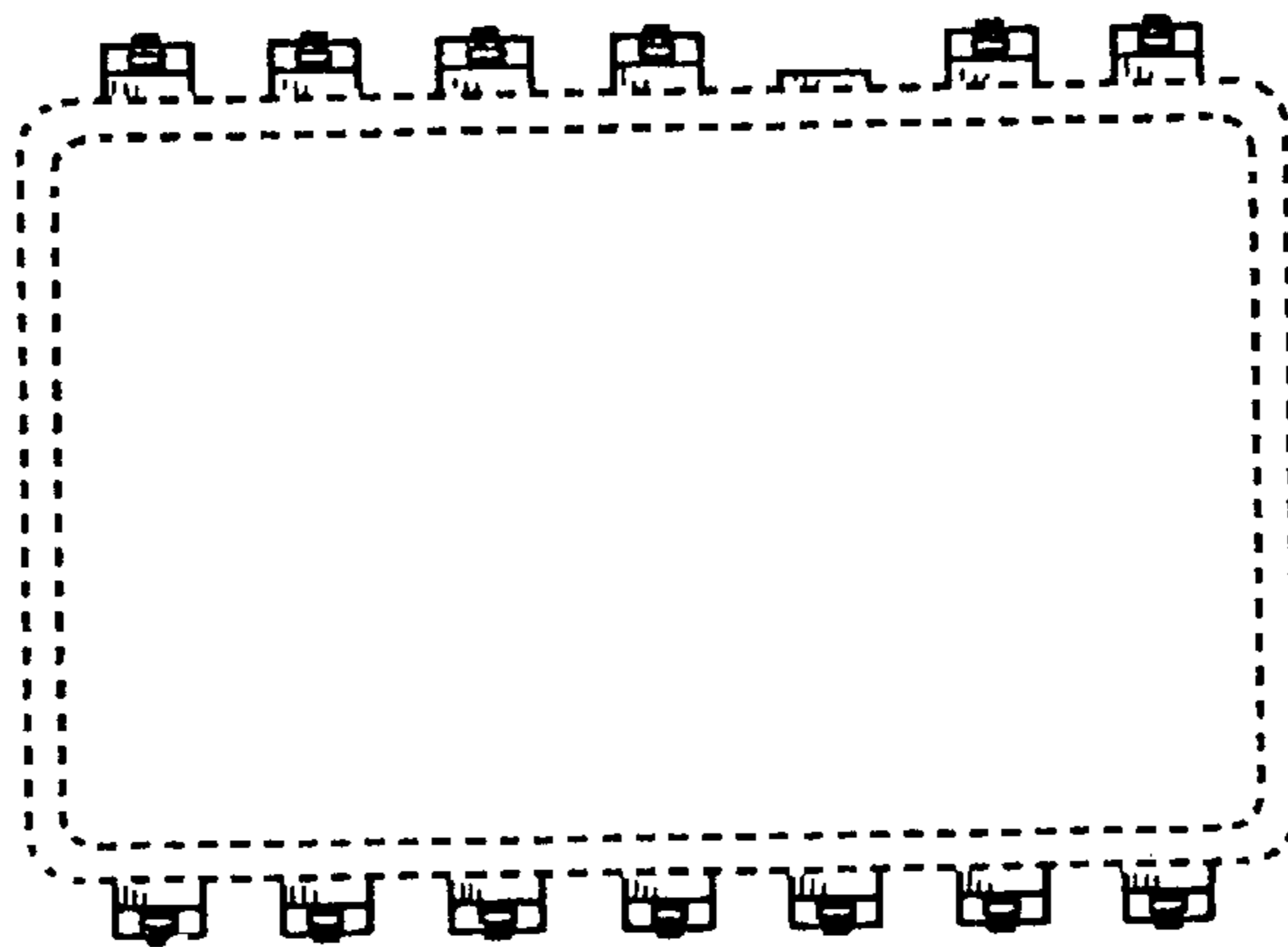
**FIG. 3**



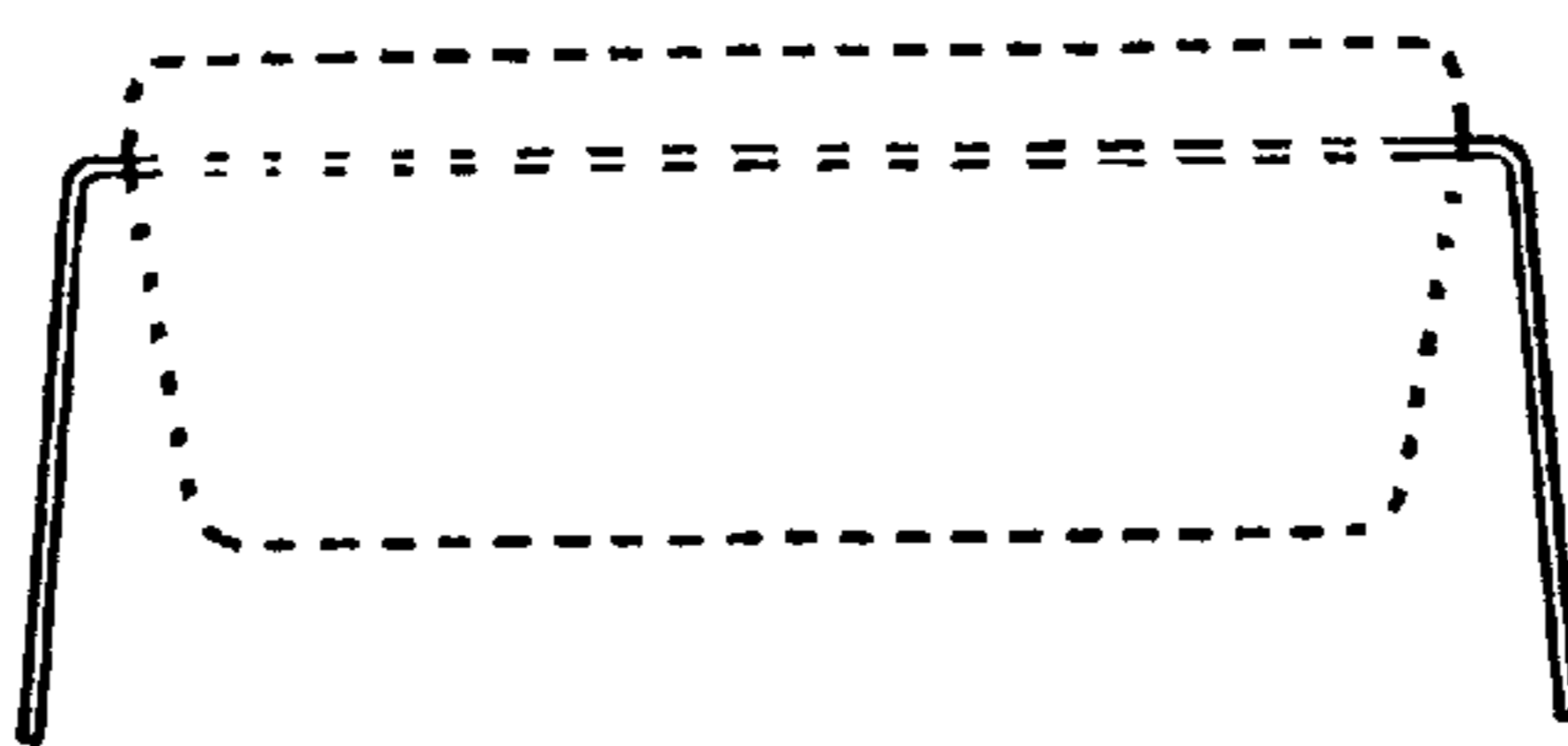
**FIG. 4**



**FIG. 5**



**FIG. 6**



**FIG. 7**

